

Advanced Power Technology, Inc.**Profile**

Advanced Power Technology, Inc.
 405 S.W. Columbia Street
 Bend, Oregon 97702
 503/382-8028
 Fax: 503/388-0364

ESTABLISHED: June 1984
 NO. OF EMPLOYEES: 69

BOARD

<u>Name</u>	<u>Affiliation</u>	<u>Position</u>
Morris Chang	Taiwan Industrial Technology Research Institute	president
Charles Cole	Julian, Cole & Stein	general partner
Ted Hollinger	Advanced Power Technology, Inc.	founder
Leib Orlanski	Freshman, Marantz, Orlanski Cooper & Klein	attorney, partner
Patrick Sireta	Advanced Power Technology, Inc.	president/CEO
Ed Snape	The Vista Group	general partner
Dave Stein	Julian, Cole & Stein	general partner

COMPANY EXECUTIVES

<u>Position</u>	<u>Name</u>	<u>Prior Company</u>	<u>Prior Position</u>
President/CEO	Patrick Sireta	TI	VP CMOS Div
VP Adv Applications and Systems	Ted Hollinger	AMD	Chief Technical Officer
VP Marketing	Thomas G. Daly	GE	Prod Mktg Mgr
VP Operations	John Hess	Seeq	Dir Operations
CFO	Robert M. Holburn	TI	Ctr WW MOS Mem
VP Engr	Dah Wen Tsang	Theta-J	Dir Research
Sales Manager	Terry Bowman	Micron	VP Sales/Mktg

FINANCING

<u>Date</u>	<u>Round</u>	<u>Amount</u>
1985	Seed	\$0.4M
1985	Round 1	\$2.5M
1986/1987	Round 2	\$8.1M
1988	Round 3	\$2.8M

Major investors include Julian, Cole & Stein; The Vista Group; Orien Ventures; 1st Chicago Investment Advisors; Sunwestern Ventures Company; J.F. Shea Company; and Mitsui & Company (U.S.A.), Inc.

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Position

president

general partner founder
attorney, partner

president/CEO general partner general partner

Prior Position

VP CMOS Div Chief Technical Officer
Prod Mktg Mgr Dir Operations Ctr WW MOS Mem Dir Research
VP Sales/Mktg

Fax: 503/388-0364

BOARD

Name

Morris Chang

Charles Cole Ted Hollinger Leib Orlanski

Patrick Sireta Ed Snape

Dave Stein

COMPANY EXECUTIVES

Position

President/CEO

VP Adv Applications

and Systems VP Marketing VP Operations CFO
VP Engr
Sales Manager

FINANCING

Date

1985

1985

1986/1987

1988

Affiliation

Taiwan Industrial Technology Research Institute

Julian, Cole & Stein

Advanced Power Technology, Inc. Freshman, Marantz,
Orlanski

Cooper & Klein

Advanced Power Techiiol(agy. Inc. The Vista Group
Julian, Cole & Stein

Name

Patrick Sireta Ted Hollinger

Thomas G. Daly John Hess

Robert M. Holburn Dah Wen Tsang Terry Bowman

Round

Seed Round 1 Round 2 Round 3

Prior Company

TI AMD

GE Seeg TI Theta-J Micron

Amount

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Advanced Power Technology, Inc. Profile

BACKGROUND

Advanced Power Technology (APT) designs, manufactures, and markets low-cost, high-power MOSFETs for advanced electric power switching applications, such as data processing and telecommunications equipment, defense systems, and variable speed electric motors.

APT has developed a family of large-die MOSFETs, that match the power and price advantages of low-speed thyristors and bipolar transistors with equivalent switching speeds. The MOSFETs feature lower on resistance and lower input capacitance, achieved with a metal-gate and 6-micron feature sizes. APT has also reduced manufacturing costs by developing a simpler MOSFET design that reduces the number of masks required.

The Company's future plans include developing a line of hybrids and insulated gate bipolar transistors (IGBTs).

Recent Highlights

Oct. 1986

March 1987

June 1987

Dec. 1987

First prototype MOSFETs produced.

Internal wafer fabrication facility fully operational.

Shipped first sample MOSFETs for evaluation

First production MOSFETs shipped to customers.

ALLIANCES; Not available

SERVICES

Design Manufacturing Final Test

MANUFACTURING

Technology

5-micron metal-gate MOS 4-inch wafers

90

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Facilities

The Company conducts all manufacturing in its Bend, Oregon, facility. Assembly for military products is done in the United States, other assembly is conducted by companies overseas.

Bend, Oregon	31,750 sq. ft.	Total area
	18,250 sq. ft.	Administration, assembly, test
	13,500 sq. ft.	R&D, engineering, wafer fabrication (including class 10 areas underhood)

PRODUCTS

<u>Device</u>	<u>Vds Volts</u>	<u>Id cont. Amps</u>	<u>Idm Amps</u>	<u>Available</u>
APT4020/4025	400	20.3 to 22.6	81.0 to 90.6	Now
APT4525/4530	450	18.5 to 20.3	74.0 to 81.0	Now
APT5025/5030	500	18.5 to 20.3	74.0 to 81.0	Now
APT40XX	400	8.9 to 28.2	35.8 to 112.7	2Q 1988
APT45XX	450	7.6 to 25.2	34.7 to 100.8	2Q 1988
APT50XX	500	7.7 to 25.2	30.5 to 100.8	2Q 1988
APT55XX	550	7.3 to 23.0	29.2 to 92.0	2Q 1988
APT60XX	600	7.3 to 21.3	29.2 to 85.2	2Q 1988
APT4008/09/30/40/85	400	7.0 to 51.4	28.0 to 205.7	3Q 1988
APT451/09/10/40/50/85	450	6.0 to 48.5	24.0 to 193.9	3Q 1988
APT501/10/12/40/50/85	500	6.0 to 46.0	24.0 to 184.0	3Q 1988
APT551/11/13/50/60	550	5.5 to 43.8	22.0 to 175.4	3Q 1988
APT601/13/15/60/70	600	4.7 to 40.3	18.8 to 161.3	3Q 1988
APT8032/40/75/90	800	10.7 to 25.7	46.8 to 92.0	3Q 1988
APT901/45/50/90	900	10.1 to 21.7	42.7 to 82.3	3Q 1988
APT1001/50/60	1000	10.1 to 20.6	40.5 to 82.3	3Q 1988
APT801/802	800	3.8 to 10.2	15.2 to 40.7	4Q 1988
APT901/902/903	900	3.4 to 9.0	13.6 to 36.0	4Q 1988
APT1001/2/3/4	1000	3.4 to 8.5	13.6 to 34.0	4Q 1988

Profile

Facilities

The Company conducts all manufacturing in its Bend, Oregon, facility. Assembly for military products is done in the United States, other assembly is conducted by companies overseas.

Bend, Oregon

PRODUCTS

Device

APT4020/4025 APT4525/4530 APT5025/5030

APT40XX APT45XX APT50XX APT55XX APT60XX

31,750 sq. ft. 18,250 sq. ft. 13,500 sq. ft.

Vds

Volts Amps

Total area

Administration, assembly, test

RSD, engineering, wafer fabrication

(including class 10 areas underhood)

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LIST OF TABLES: Do Not Remove

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